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PATENT APPLICATION

Applicants: **Nallan et al.**

Case no.: **7017/ETCH/CONE**

Serial No.: **10/092,795**

Filed: **March 6, 2002**

Group Art Unit: **2812**

Examiner: **Not yet assigned**

Title: **METHOD OF PLASMA ETCHING OF HIGH-K DIELECTRIC  
MATERIALS WITH HIGH SELECTIVITY TO UNDERLYING LAYERS**

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REQUEST FOR CORRECTED FILING RECEIPT

Applicants enclose herewith a copy of the Filing Receipt received in the above-captioned application and request a corrected Filing Receipt be issued to include the information indicated in red ink. Specifically, please change the attorney docket number to: 7017/ETCH/CONE.

Respectfully submitted,

*[Signature]*  
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*5-21-02*  
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Please continue send all correspondence to:  
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Santa Clara, CA 95052

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/092,795	03/06/2002	2812	1076	7017/ETCH/GORE- CONE	4	34	4

CONFIRMATION NO. 3410

FILING RECEIPT



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Applicant(s)

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Assignment For Published Patent Application

Applied Materials, Inc.;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 04/09/2002

Projected Publication Date: 09/11/2003

Non-Publication Request: No

Early Publication Request: No

Title

Method of plasma etching of high-K dielectric materials with high selectivity to underlying layers

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